Recent Progress

- **Mosaix Probe Card**
  All simulations documented in a draft Keynote document, shared with MPI, expected feedback tomorrow

- **Probe Card FPCs - PCBs**
  8+ versions designed & simulated to optimize signal integrity and have compatibility with ITS3 test systems
  4x version submitted to CERN PCB Workshop should be available around beginning of March (1x mixed panel)
  all other versions are on hold

  Discussed with ITS3 members for the design & simulation of the breakout board to route HS-data to a scope
  offered help, no feedbacks so far

- **Initial preparation of the testing setup in DSF, to be continued**
  Pad Wafer loaded – WP SW guarantess machine operation remotely, has to be polished (ongoing)
  Cantilever Probe Card will be mounted tomorrow, this will trigger:
    - Preparing the projects for contacting pad wafers
    - Studies on contacting reliably pad wafers manually
    - Operation of the machine on Pad Wafers through Software